

## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL03C030CB3GNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 3pF, 50V, ±0.25pF, C0G, 0201

## A. Samsung Part Number

<u>CL</u> <u>03</u> <u>C</u> <u>030</u> <u>C</u> <u>B</u> <u>3</u> <u>G</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor		
2	Size	0201 (inch code)	L: 0.6 ± 0.03 mm	W: $0.3 \pm 0.03 \text{ mm}$
3	Dielectric	C0G	8 Inner electrode	Cu
4	Capacitance	<b>3</b> pF	Termination	Cu
⑤	Capacitance	<b>±0.25</b> pF	Plating	Sn 100% (Pb Free)
	tolerance		Product	Normal
6	Rated Voltage	50 V	Special	Reserved for future use
7	Thickness	$0.3 \pm 0.03$ mm	① Packaging	Cardboard Type, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition	
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms	
Q	460 min		
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	300% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	COG		
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)		
Adhesive Strength	No peeling shall be occur on the	200g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change :	Bending to the limit (1mm)	
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	1) Sn63Pb37 solder	
	is to be soldered newly	235±5℃, 5±0.5sec.	
		2) SnAg3.0Cu0.5 solder	
		245±5℃, 3±0.3sec.	
		(preheating : 80~120℃ for 10~30sec.)	
Resistance to Capacitance change :		Solder pot : 270±5℃, 10±1sec.	
Soldering heat	within ±2.5% or ±0.25pF whichever is larger		
	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change :	Amplitude : 1.5mm
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)
Humidity	Capacitance change :	40±2℃, 90~95%RH, 500+12/-0hrs
	within ±5% or ±0.5pF whichever is larger	
	Q: 230 min	
IR : 1000Mohm or 50Mohm $\cdot  \mu$ F		
	Whichever is Smaller	
Moisture	Capacitance change :	With rated voltage
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs
	Q: 110 min	
	IR : 500Mohm or 25Mohm · μF	
	Whichever is Smaller	
High Temperature	Capacitance change :	With 200% of the rated voltage
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature
	Q: 230 min	1000+48/-0hrs
	IR : 1000Mohm or 50Mohm · μF	
	Whichever is Smaller	
Temperature	Capacitance change :	1 cycle condition
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25 °C
	Tan δ, IR : initial spec.	→ Max. operating temperature → 25°C
		5 cycle test

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\!\!\mathrm{C}$  , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.